

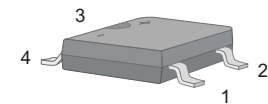
ABS201 THRU ABS210

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 2 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MECHANICAL DATA

- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg 0.0031oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	ABS201	ABS202	ABS204	ABS206	ABS208	ABS210	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_L = 100\text{ }^\circ\text{C}$	I_O	2.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50						A
Forward Voltage per element @ $I_F = 2.0\text{A}$	V_F	1.0						V
Maximum DC Reverse Current @ $T_A = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = 125\text{ }^\circ\text{C}$	I_R	5.0 100						μA
Typical Junction Capacitance (Note1)	C_j	25						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	65						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad.

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Fig.1 Average Rectified Output Current Derating Curve

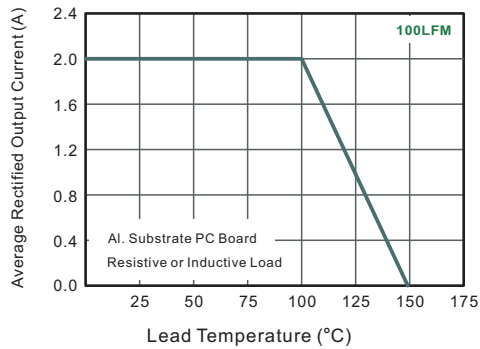


Fig.2 Typical Reverse Characteristics

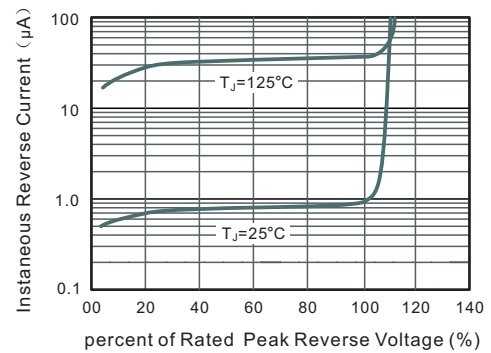


Fig.3 Typical Instantaneous Forward Characteristics

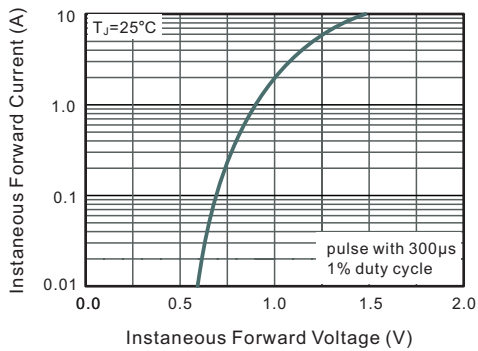


Fig.4 Typical Junction Capacitance

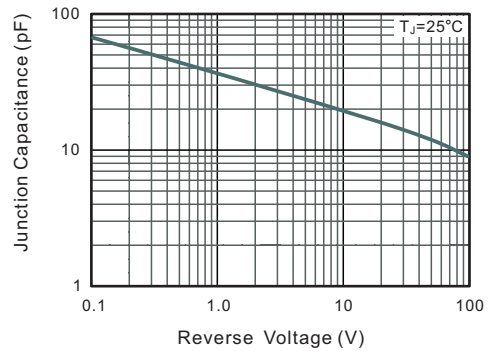
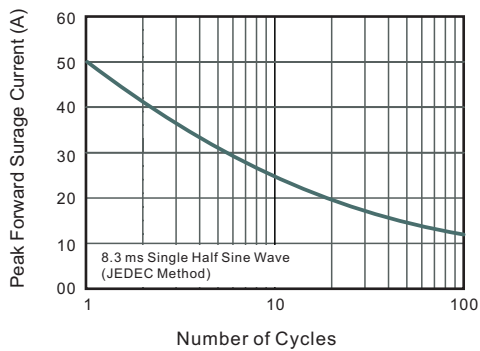


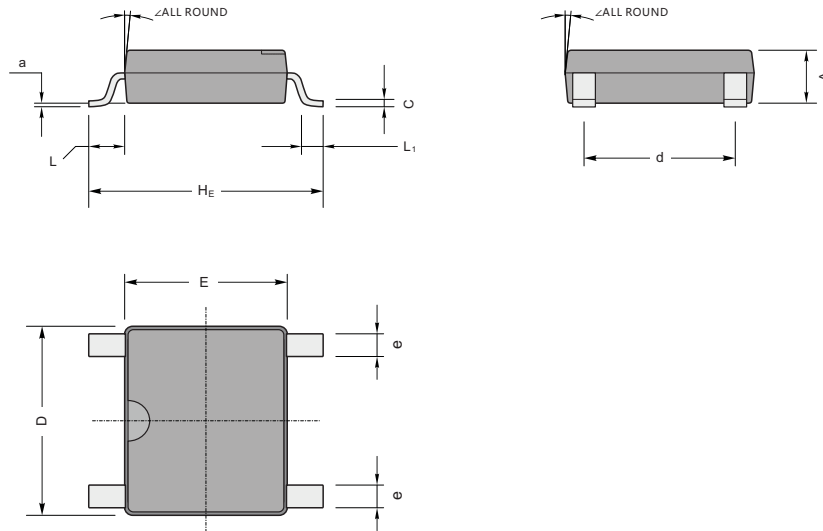
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



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PACKAGE OUTLINE

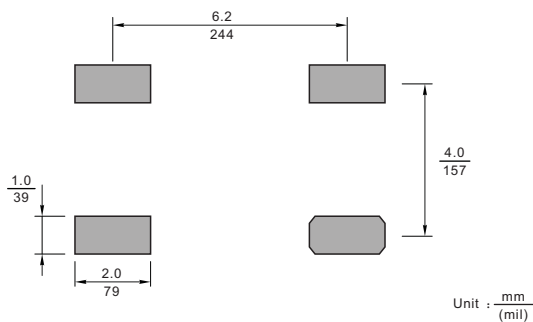
Plastic surface mounted package; 4 leads



ABS/LBF mechanical data

UNIT		A	C	D	E	H_E	d	e	L	L_1	a	\angle
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	
	min	51	5.9	193	166	236	150	20				

The recommended mounting pad size



单击下面可查看定价，库存，交付和生命周期等信息

[>>YONGYUTAI\(永裕泰\)](#)